

SMTA China South Conference 2008



26-30 August 2008
Shenzhen Convention & Exhibition Centre,
Shenzhen, China

SMTA China South Conference 2008 Program					
	26 August (Tuesday)	27 August (Wednesday)	28 August (Thursday)	29 August (Friday)	30 August (Saturday)
Technology Conference	10:00-16:00				
Vendor Conference	10:00-17:00				
SMTA Engineer Certification	09:00-17:00				
SMTA HK Chapter Annual Reception		17:00-20:00			
Trade Show	NEPCON South China 2008				
Golf Tournament					8:00-17:00

The SMTA China will organize the SMTA China South Conference 2008 in Shenzhen on 26-30 August, 2008. This timely event will be held in conjunction with NEPCON South China and will address the industry's most pressing issues concerning electronics manufacturing, advanced packaging and lead-free reliability.

Technology Conference/Vendor Conference Topics (26-28 August 2008)

- 01005 Assembly
- 3D SiP (System in Package)
- Challenges of PCB Fabrication Technology and Surface Finish
Component Supply Integrity
- Cost Reduction Initiative
- Advanced Low I/O Packaging
- Flex Circuit Assembly

- Market Trends in Assembly Manufacture
- Manufacturing Engineering
- Materials and Process Characterization
- Pb Free Processes and Product Reliability
PoP (Package on Package)
- Process Control Excellence
- Production and Supply Chain Management
RoHS Compliance and Materials
- Risk Free Rework/Repairing
- State of Art Inspection and Failure Analysis

SMT Engineer Certification (26-28 August 2008)

SMTA Engineer Certification program is a three-day offering consisting of a 1.5-day refresher workshop on topics in SMT Processes. The program concludes on days two and three with an open and closed book examination.

This is not an entry-level program. Basic algebra will be used in the workshop and examination. This challenging examination requires both written answers and calculations with the intent to enable the attendee to establish competitive credentials as "Certified" by the SMTA in SMT Processes

Enquiry and Registration: E-mail to peggy@smta.org

SMTA 华南高科技会议 2008



2008年8月26—30日
中国深圳会展中心

SMTA 华南高科技会议 2008 节目					
	8月26日 (星期二)	8月27日 (星期三)	8月28日 (星期四)	8月29日 (星期五)	8月30日 (星期六)
高科技会议	10:00-16:00				
高科技设备技术研讨会	10:00-17:00				
SMT 工程师认证课程	09:00-17:00				
SMTA 香港分会周年酒会		17:00-20:00			
展览会	第十四届华南国际电子生产设备暨微电子工业展				
高尔夫球比赛					08:00-17:00

SMTA 中国将于 2008 年 8 月 26—30 日在第十四届华南国际电子生产设备暨微电子工业展览会期间举行「SMTA 华南高科技会议 2008」，高科技会议将有来自世界各国顶尖专家发表有关电子工业及制造、先进封装技术及无铅技术之可靠性等范畴之论文。

高科技会议/高科技设备技术研讨会主题(2008 年 8 月 26-28 日)

- 01005 组装
- 三维系统内封装
- 印刷线路板的生产技术及表面加工的挑战
- 完整器件供应
- 成本减低的积极性

- 先进低联口封装
- 柔性线路组装
- 组装生产的市场趋势
- 制造工程技术
- 材料及工艺特性
- 无铅过程及产品可靠性
- 叠装片封装
- 卓越的生产工艺控制
- 生产和供应链的管理
- 电子信息产品污染控制方法及物料
- 免危的重造及返修
- 最先进的检查及失效分析技术

SMTA 工程师认可证书课程(2008 年 8 月 26-28 日)

SMTA 工程师认可证书课程是一个为期三天之 SMT 工艺重温工作坊，考试于课程第二及三日举行；此课程并非初级课程，考试内容需运用代数学，但可使用有关计算机；考试合格可获得 SMTA 认可 SMT 工艺工程师资格。

查询及报名：电邮至 peggy@smta.org